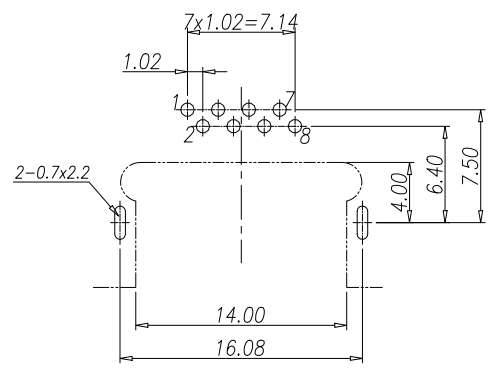
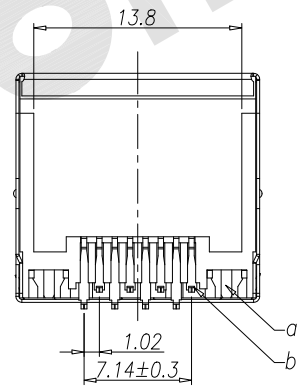
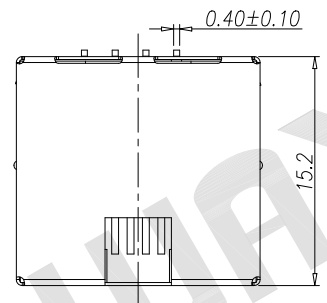
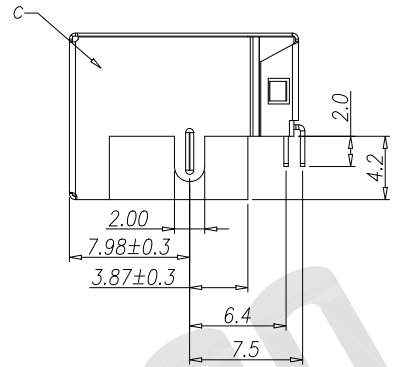
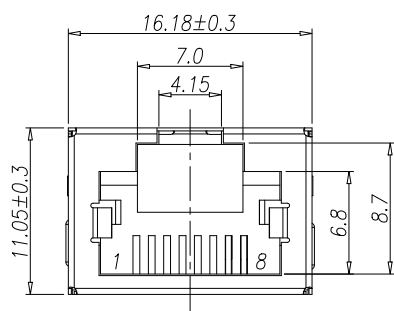


REV.	DESCRIPTION	DRAWN	CHECKED	APPROVED
A	NEW RELEASE	JLZ 03/24/16'	~	



Recommend PCB Layout  
(Jack Top View)  
Tolerance: ±0.05mm

**Description:**

Ultra Low Profile, Offset RJ45, H=11.05, Shielded, Sink: 4.2

**Material:**

- Housing Material: High Temp Nylon, LCP, UL94V-0
- Contact Material: Phosphor Bronze T-0.35mm Thickness
- Plating: Selective Gold Plating on Contact Area
- Gold Plating Thickness: (Au 1u", 3u", 6u", 15u", 30u", 50u")
- 100u" Min. Matte Tin Plated on Soldering Area
- 50u" Min. Nickel Plated Overall
- Shell: Copper Alloy, 0.25mm Thickness

**Electrical:**

- Voltage Rating: 125 V AC RMS
- Current Rating: 1.5 Amp
- Contact Resistance: 30mΩ Max.
- Insulation Resistance: 500MΩ Min. @ 500 VDC
- Dielectric Withstanding Resistance: 1000 VAC RMS 50Hz, 1 Min.

**Mechanical:**

Durability : 750 Cycles Min.

**Environmental:**

- Storage Temperature : -40°C to +85°C
- Operation Temperature: -40°C to +85°C

Reflow Soldering Temperature : 255°C to 265°C, 5-10 seconds

MJ7021R - X X X X X X X

No. of Positions	Positions Loaded	Shield	LED	Insulator Material	Contact Plating	Packing Style
4,6,8	2,4,6,8	0 - w/o Shield	0 - Without	1 - PBT	1 - 1μ"	1 - Tape & Reel
		1 - Shielded w/o EMI	1 - G/Y	2 - PA66	2 - 3μ"	2 - Plastic Tray
		2 - Shielded w/ EMI	2 - Y/G	3 - PA46	3 - 6μ"	
		3 - Half Shielded	3 - Other	4 - LCP	4 - 15μ"	
				5 - PA9T	5 - 30μ"	

GENERAL TOLERANCE		ANGLE TOLERANCE		PROJECTION	TITLE
X.	±0.60	X.	±5°	mm	Ultra Low Profile, Offset RJ45, H=11.05mm, Shielded, Sink: 4.2mm
.X	±0.38	.X	±3°		
.XX	±0.25	.XX	±2°		
DRAWING TYPE		CUSTOMER		SHEET SIZE	SERIES
SCALE		1:1		A4	OFFSET SERIES
DRAWING NO.		MJ7021R-XXXXXXX			

**WAYCONN CO.,LTD**